



MATERIAL DECLARATION

			PART NUMBER AS4C128M32MD2A-xxBIN	Approved by: quality@alliancememory.com		PART WEIGHT (mg)		196.636
No.	Material Name	Supplier	Material Content (Element)	CAS Number	Material Mass (mg)	Material Mass (%)	Substance wt (%)	Substance wt (mg)
1	Chip	Alliance Memory	Silica	7440-21-3	19.644	9.990%	100%	19.644
2	Substrate	Ryowa/BT	Resin	None	32.052	16.300%	25.05%	8.029
			Fiber Glass	None			16.70%	5.353
			Mask	7727-43-7			7.20%	2.308
			Dipropylene glycolmonomethyl ether	34590-94-8			3.84%	1.231
			Talc containing noasbestiform fibers	14807-96-6			0.64%	0.205
			Resin	Trade seacret			3.52%	1.128
			Morpholine derivative	Trade seacret			0.64%	0.205
			Naphthalene	91-20-3			0.16%	0.051
			Cu Trace	7440-50-8			8.00%	2.564
			Ni plating	7440-02-0			1.21%	0.388
			Au plating	7440-57-5			0.16%	0.051
			Cu plating	7440-50-8			32.88%	10.539
3	FOW	Nitto / EM310	Epoxy Resin	Trade secret	2.537	1.290%	25.000%	0.634
			Synthetic rubber	Trade secret			5.000%	0.127
			Pheol resin	14807-96-6			25.000%	0.634
			Silica, amorphous	7631-86-9			45.000%	1.141
4	Die attach film	Nitto/EM760	Acrylic resin	Trade Secret	1.278	0.650%	50.00%	0.639
			Silica, amorphous	7631-86-9			45.00%	0.575
			Phenol resin	Trade Secret			5.00%	0.064
5	Bonding wire	MKE	Au	7440-57-5	0.629	0.320%	99.999%	0.629
			Beryllium	7440-41-7			0.0008%	0.00001
6	Molding Compound	Sumitomo / G760LB	Epoxy Resin	Trade secret	126.476	64.320%	8.00%	10.118
			Phenol Resin A	Trade secret			3.00%	3.794
			Phenol Resin B	Trade secret			3.00%	3.794
			Carbon Black	1333-86-4			0.50%	0.632
			Metal Hydroxide	Trade secret			8.00%	10.118
			Silica A	60676-86-0			75.00%	94.857
			Silica B	60676-86-0			2.50%	3.162
7	Solder ball	Senju/M705	Sn	7440-31-5	14.020	7.130%	96.50%	13.529
			Ag	7440-22-4			3.00%	0.421
			Cu	7440-50-8			0.50%	0.070

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